

PLASTIC PACKAGE BASE, AIR CAVITY TYPE PACKAGE AND THEIR MANUFACTURING METHODS

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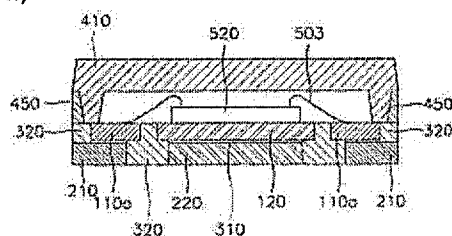
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The plastic package base includes: a first lead frame including at least one first unit body comprising a first pad required for chip bonding and first leads acting as internal terminals, arranged around the first pad and spaced a predetermined distance away from the first pad; a second lead frame including at least one second unit body comprising a second pad and second leads acting as external terminals and bonded to the first lead frame so that the second pad and the second leads correspond to the first pad and first leads of the first lead frame; and a plastic body mold-shaped in spaces between the first and second lead frames so that the top surfaces of the first leads, the top surface of the first pad, the bottom surfaces of the second leads, and the bottom surface of the second pad are exposed on the surfaces of the plastic body and the top surface of the plastic body is not higher than the top surfaces of the first leads.



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